Project title: High Performance High Current CW polarized photocathodes for Electron Ion Colliders

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FY25 NP SBIR/STTR PI Exchange Mtg

Phase II Technical Point of Contact:

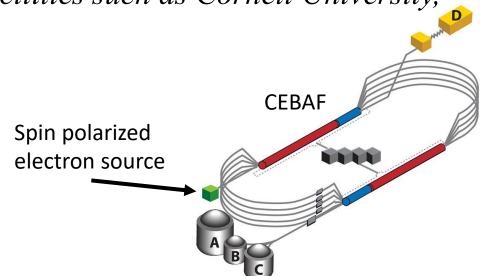
Michelle Shinn, e: Michelle.Shinn@science.doe.gov

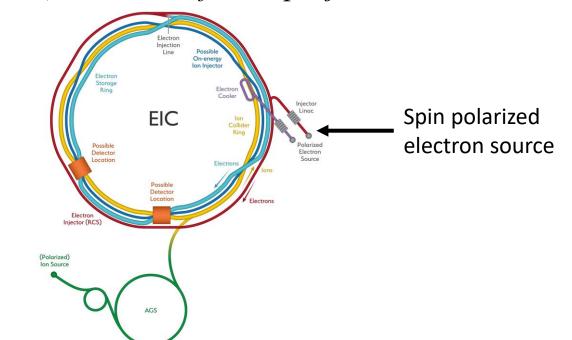
Need Addressed: Higher Performance Photocathodes for Spin Polarized Sources

• Electron Ion Colliders (EIC) need high efficiency, narrow energy distribution source of spin-polarized electrons for examining properties of fundamental particles such as Quarks, Nuclei, Bosons, etc.

• Enhanced photoemission properties will also benefit the current and future operation of CEBAF at Jefferson National Laboratory (JLab) as well as future projects at other

facilities such as Cornell University,





BNL Photocathode system allows characterization for QE and ESP

The load lock system allow us to exchange samples without breaking the vacuum of the activation and polarimeter vacuum chambers.

The UHV system (10⁻¹¹ Torr) consist of three vacuum chambers: the load lock the activation chamber the Mott polarimeter chamber

The retarding field Mott polarimeter is operated with an Au target maintained at a voltage of 25 kV.

It allows operation with up to 4 channeltrons detectors for the measure of the electron spin polarization.

For III-V semiconductors measurement only two channeltrons are used.

Mott Polarimeter

Activation Chamber

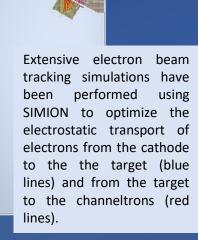
Load Lock

Photons used to illuminate the photocathode during the photoemission experiments are produced by a tungsten halogen lamp. A monochromator is used to select the central emission wavelength with bandwidth of about 10

A combination of a linear polarizer and a tunable liquid crystal retarder are used to produce the left- and right-handed circularly polarized light required to produce spin polarized electrons.

Proprietary and Confidential to Structured Materials Industries, Inc.

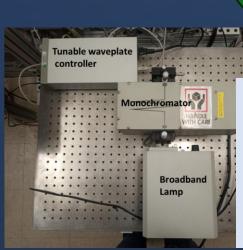




The activation chamber hosts the sample holder used during activation and characterization of the samples. The holder is equipped with a BN heater capable of bringing the samples to temperatures above 600 C.

Sample can be negatively biased and a calibrated K Type thermocouple is used to measure the temperature of the sample.

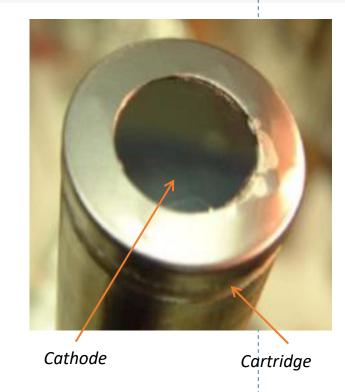
Cesium vapors from a metal chromate dispenser and high purity oxygen coming from leak valve are used to perform the Negative Electron Affinity activation of the samples.



SMI Led Team's innovative solution



GaAs	5 nm	p = 5x10 ¹⁹ cm ⁻³
GaAs _{0.62} P _{0.38}	4 nm	p = 5x10 ¹⁷ cm ⁻³
GaAs	4 nm	p = 5x10 ¹⁷ cm ⁻³
GaAs _{0.81} P _{0.19}	300 nm	p = 5x10 ¹⁸ cm ⁻³
AIAs _{0.78} P _{0.22}	65 nm	p = 5x10 ¹⁸ cm ⁻³
GaAs _{0.81} P _{0.19}	55 nm	p = 5x10 ¹⁸ cm ⁻³
GaAs _{0.81} P _{0.19}	2000 nm	p = 5x10 ¹⁸ cm ⁻³
GaAs->GaAs _{0.81} P _{0.19}	2750 nm	p = 5x10 ¹⁸ cm ⁻³
GaAs buffer	200 nm	p = 5x10 ¹⁸ cm ⁻³
GaAs substrate		p > 1x10 ¹⁸ cm ⁻³



30 pairs

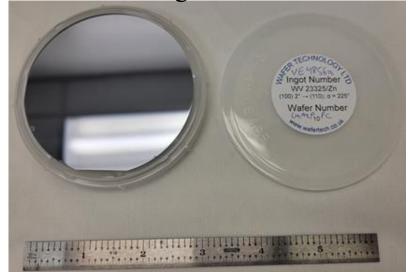
- Highly efficient spin polarized narrow energy distribution electron source emits electrons upon excitation by a circularly polarized laser beam with energy close to the energy band gap requiring negative electron affinity (NEA) at the surface of the semiconductor:
- ✓ BNL designed super lattice distributed bragg reflector (SL-DBR) structure uses strain compensation to mitigate relaxation of strained layer
- ☑ This allows for increased number of SL pair for increased optical absorption and hence increased QE
- Due to the reduced strain (+/- 0.7%) Heavy Hole and Light Holes are separated by only ∼66 meV

Major Goals and Objectives of this Project

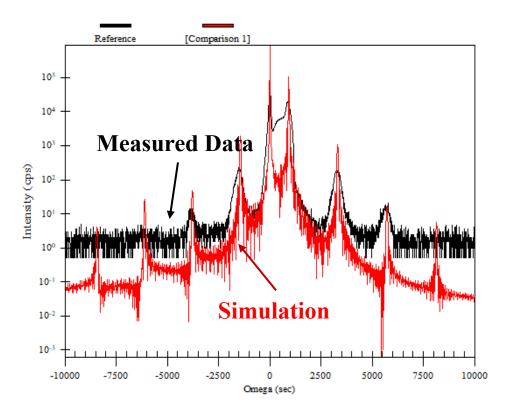
- Refine device design and model-through material and device characterization/performance feedback with a focus on tuning composition, superlattice (SL) and DBR/F-P layer thicknesses; as appropriate to maximize QE, ESP and lifetimes for operation at 780 nm.
 - Target Performance Parameters
 - ESP 90%
 - QE -5%
- Mitigate/eliminate oxide formation on top of the device which is suspected/anticipated to decrease the QE and ESP of the photocathode (Starting by using vacuum packaging) and understand impact on ESP if any.
- Refine structure tuning to provide optimal performance at 780 nm.
- Determine the commercializable performance specifications of the photocathodes through testing (QE, upper current limit, ESP, operational lifetime, bunch charge achievable, packaging and preparation and compare to commercial values.
- Demonstrate high performance spin polarized photocathodes at BNL testing laboratory and potentially sample to other interested groups including Jefferson National Lab, Cornell University, and others yet to be determined or suggested by DOE.
- Refine Phase III production and commercialization pathways evaluate additional market.

Growth of GaAs/GaAsP SL on base structure

- GaAs_{0.81}P_{0.19} composition, growth rate and doping were calibrated, and base structures were grown.
- Following this GaAs_{0.62}P_{0.38} was calibrated, and SL structures were grown and optimized on existing base structures.
- Wafers, with full structure except DBR, were sent to BNL for testing.



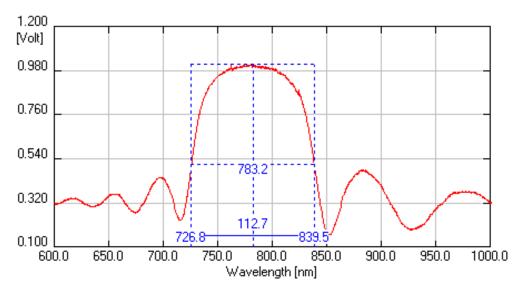
Photograph of 3-inch full wafer structure except DBR



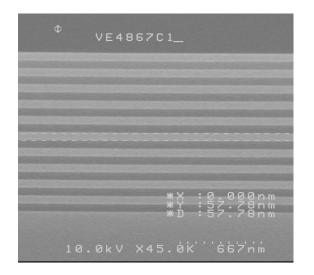
X-ray measured data (black) compared to simulation (red) of full structure except DBR. The measured peak spacing and position match up indicating thickness and composition is close to simulation data.

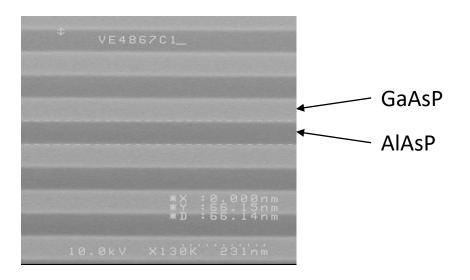
DBR calibration

- AlAs_{0.81}P_{0.19} was calibrated and wafers of DBR on base structure were grown.
- Thickness was adjusted to target reflectance at 780 nm.



Reflectivity of DBR regrown on base wafer centered near target 780 nm.

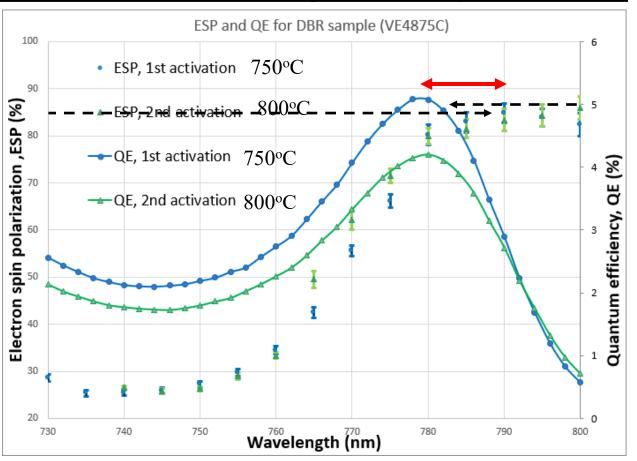




SEM image of cross section of DBR calibration run shows good uniformity and correct layer thicknesses.

ESP & QE Photocathodes Results

ESP and QE Vs Wavelength for sample with DBR



Sample is not Arsenic (As) capped and oxide is likely formed at the DBR-SL interface and surface.

Heat clean at <600 C will likely not remove all oxide (reported temperatures are for the heater not the sample).

To meet SBIR ideal specs: Align the peaks ~780 Increase QE >5% (if not 10%) and push ESP >90%

Phase I&II Approach to Increase ESP and QE

Phase I demonstrated base calculated structured with great success. Several parameters have been tested to further improve ESP, QE, and structure reproducibility. The rationale is as follows:

- C doping was tested as literature reports indicate larger optical absorption compared to Zndoped layer;
 - Zn does not incorporate easily in DBR AlAsP layers;
- **Performed 1-step growth:** no interruption (for measurement) between DBR and SL layers to mitigate possible contamination;
- **Tested modified SL-DBR structures** that uses a slightly larger strain (± 0.8%) which increases HH-LH separation up to ~77 meV;
- Increased the number of DBR layers to further increase the reflectivity;
- Sealed packaging of wafers to mitigate surface oxidation and facilitate NEA formation during activation.
- Phase II focused on refinement to theory, structures overall refinements, and reproducibility.

Best of ESP & QE data

	QE (%)	ESP (%)	FoM=QExESP ²
SMI	4.5	85	3.26 % @ 780 nm
SMI	13.5	65	5.70 % @ 790 nm
SMI	5.5	82	3.70 % @ 790 nm
Others			
BNL/SNL	15.5	62	5.96% @ 776 nm
JLab	2.9	82	1.92% @ 785 nm



References:

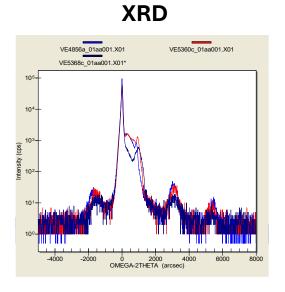
- 1. Jyoti Biswas, Luca Cultera, et al., AIP Advances 13, 085106 (2023).
- 2. W. Liu, et al., Appl. Phys. Lett. 109, 252104 (2016).
- 3. B. Belfore et al., Appl. Phys. Lett., DOI: 10.1063/5.0170106

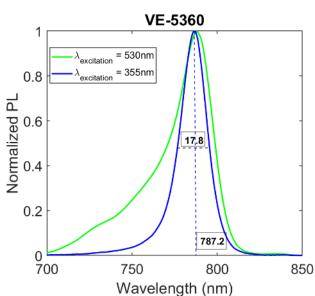
Pictures from left full structures sealed in N2 and never exposed to air, Full structures used for characterization and exposed to air and calibration structures.

Batch 1: Photocathode Structures

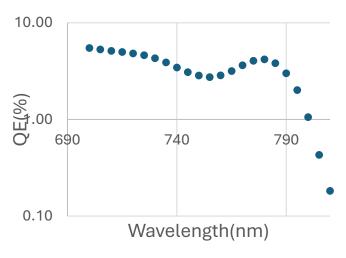
- Explored C doping rather than Zn for higher QE: This investigation into using C as a dopant instead of Zn to improve the QE of the device.
- ➤ Nitrogen package to mitigate surface oxidation: A "nitrogen package" to prevent the surface of the material from reacting with oxygen (oxidation), which can degrade performance.
- ➤ Different design with increased P content (up to 44%) for higher heavy hole (HH)- light hole (LH) separation: This batch utilized a modified design where the P content in a specific layer was significantly increased (up to 44%). The purpose of this increase was to achieve a higher "Heavy Hole-Light Hole (HH-LH) separation", which can influence device performance characteristics like polarization.

Batch 1 photocathode test data PL



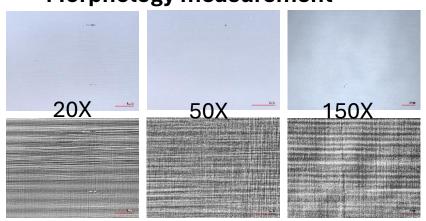


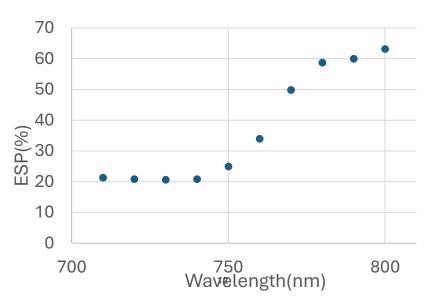
QE spectral response



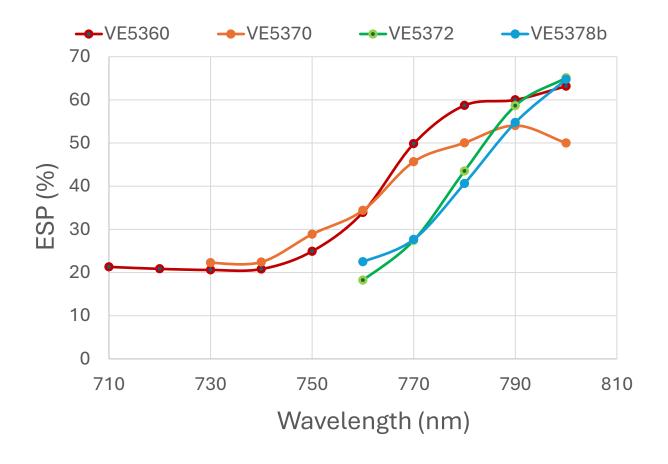
ESP spectral response

Morphology measurement





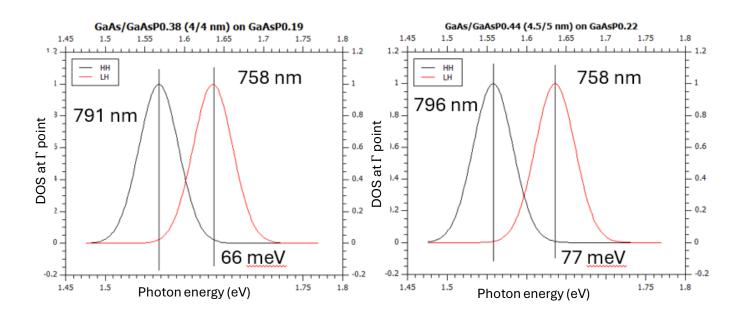
Summary of ESP from cathodes of Batch 1



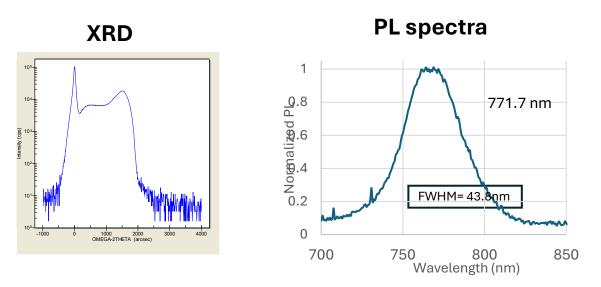
A redesigned structure, featuring increased Phosphorus (P) content (up to 44%) to enhance Heavy Hole-Light Hole (HH-LH) separation, unfortunately led to low ESP. A potential explanation for this reduced ESP is that the elevated P content may have amplified the lattice mismatch, thereby compromising the interface quality of the subsequent layers.

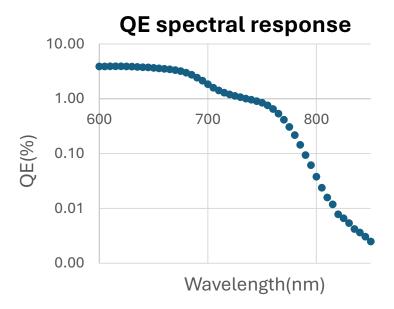
Batch 2: Change of SL structure

- ➤ Increase in the P concentration in the pseudo-substrate: 19% to 22%
- ➤ Increase P concentration in the SL: **38**% to **44**%
- > Simulations predict an increase in HH-LH separation: 66 meV to 77 meV

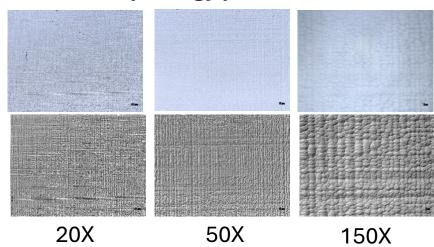


Test results from Batch 2 photocathodes





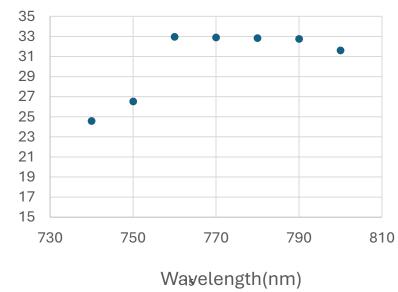
Morphology profile



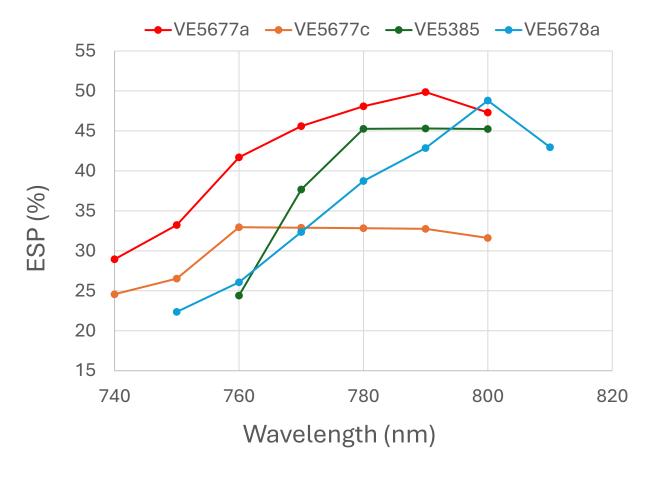
Higher roughness is visible, which probably leads to depolarization

ESP(%)

ESP spectral response



Summary of ESP from cathodes of Batch 2

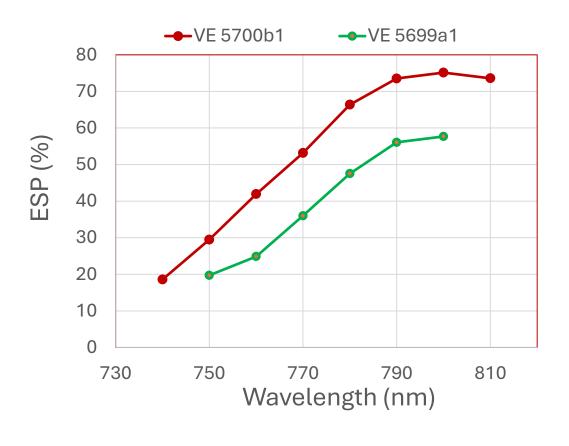


Spacer layer description:

- VE5677a GaAsP28
- VE5677c GaAsP28
- VE5385 GaAsP22
- VE5678a GaAsP19

Photocathodes with elevated phosphorus (P) content in the buffer layer exhibit higher ESP at shorter wavelengths, as their ESP decreases more gradually compared to cathodes with lower P content. However, GaAsP cathodes with 28% P show lower overall ESP, likely due to increased surface roughness in the pseudosubstrate, as observed in surface morphology maps.

Comparison of ESP performance from samples grown on same wafer using different buffer/spacer



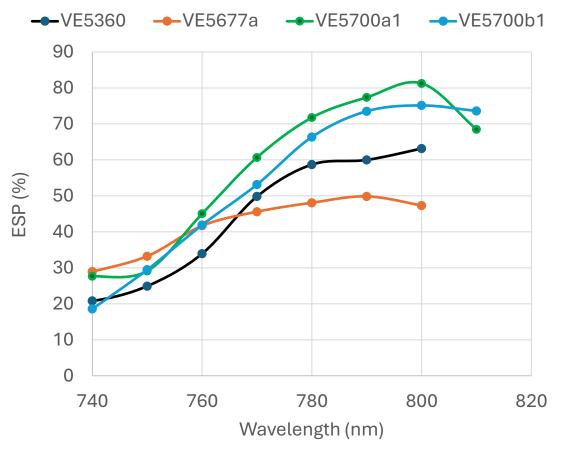
Description of spacer layer:

VE 5699a1: GaAsP19

VE 5700b1: Al10GaAsP19

Higher ESP observed from cathode with $Al_{10}GaAsP_{19}$ as spacer, which supports the idea that this **spacer layer acts as a barrier to the diffusion of electrons into the superlattice layers**; thereby preventing any dilution of spin polarization of electrons emitted from the GaAs wells in the SL.

Comparison of ESP performance from the samples with highest ESP from different batches 1, 2 and 3

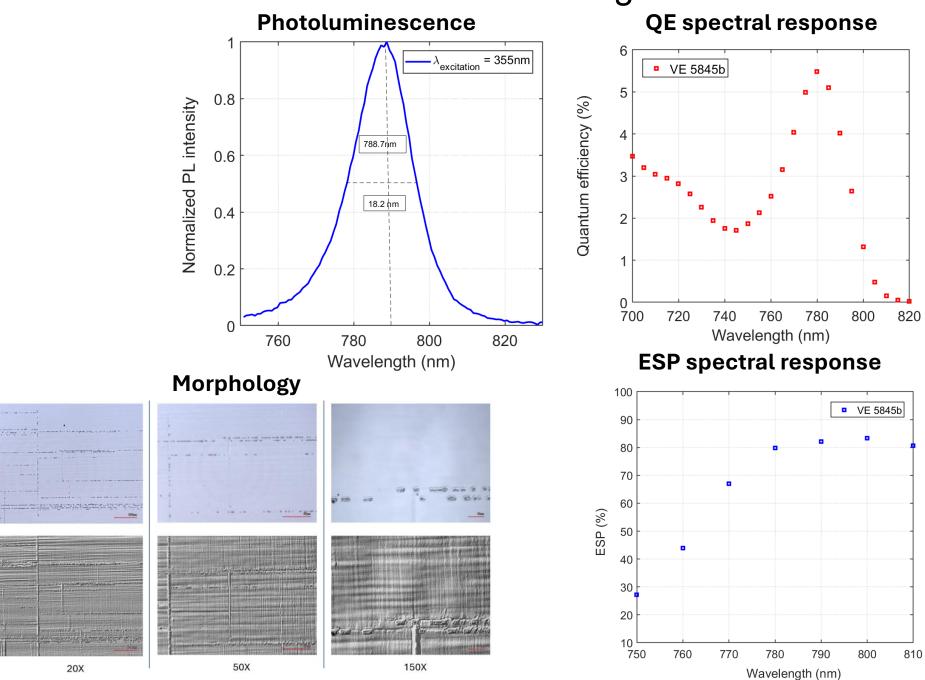


Description of spacer layer:

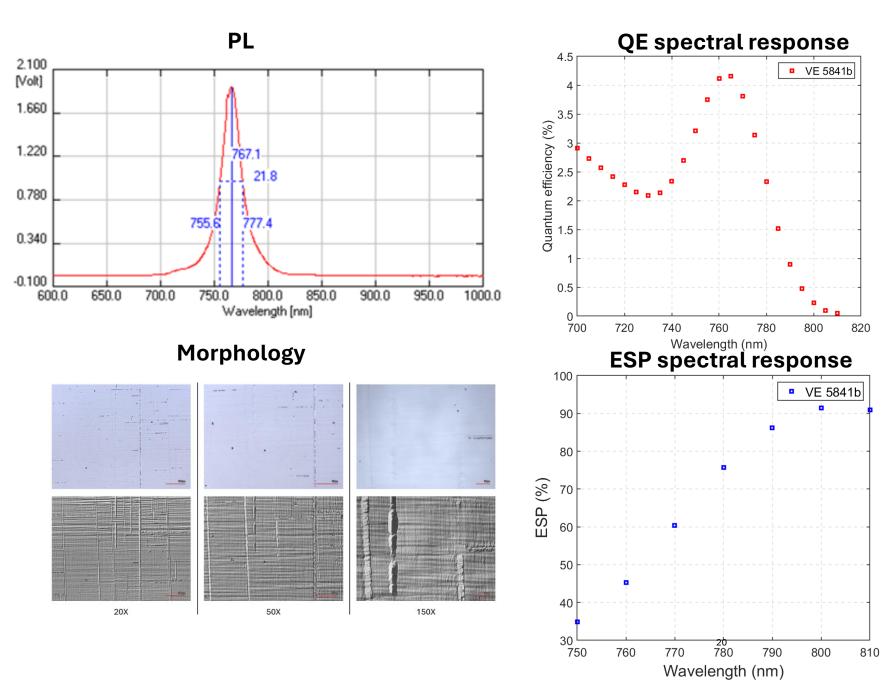
- VE5360 GaAsP19
- VE5677a GaAsP28
- VE5700a1 Al10GaAsP19
- VE5700b1 Al10GaAsP19

- Highest ESP observed from cathodes, which uses Al₁₀GaAsP₁₉ as the spacer layer.
- Increasing the P conc. in the spacer layer increases the ESP at shorter wavelengths but due to increased surface roughness overall ESP is lower from cathodes with higher P conc.

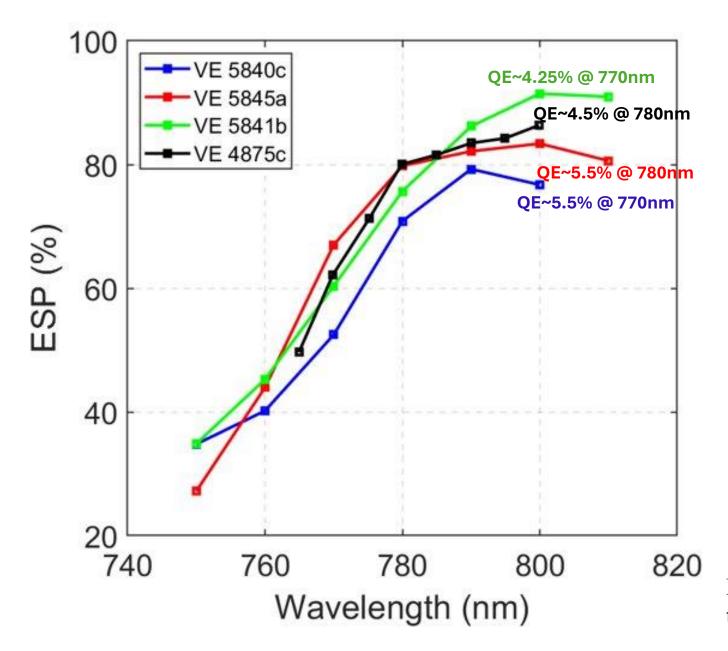
Batch 4 Photocathode testing



SMI VE5841b: buffer GaAsP19



ESP & QE performance comparison – Phase I vs Phase II



Description of spacer layer:

- VE5841b GaAsP19
- VE5840c GaAsP19
- VE5845a A115GaAsP19
- VE4875c GaAsP19 Phase I

			Fluence of Spin Polarized	
Sample	ESP	QE	Electrons per 100 Incident	
No.#	(%)	(%)	Photons	
VE5841b	92	4.25	3.91	
VE4875c	85	4.5	3.825 (Phase I)	
VE5845a	82	5.5	4.51	
VE5840c	79	5.5	4.345	

Phase II: Net ESP/photon is > 15% higher than Phase I

Outline of results and observations

We learned several things that influence the performance of the photocathode:

Phase I: Initial Growth and SL-DBR Structure Testing

We successfully grew and tested the SL-DBR structure, demonstrating an ESP greater than 80% at wavelengths longer than 790 nm and a QE exceeding 4.5% at 780 nm.

Phase II: Advanced Material Development and Optimization

- (a) Replacement of C doping in place of Zn no observable impact.
- (b) Nitrogen packing: Improves QE
- (c) High P (44% from 19%) to increase HH-LH separation to increase ESP High QE but net reduced ESP due to surface degradation due to lattice mismatch.
- (d)P at 28% interface quality in the superlattice still compromised resulting in low ESP.
- (e) Increase the bandgap of the spacer layer by adding Al to GaAsP layer between the DBR and FP superlattice structures which was expected to prevent spin polarized electrons from reabsorbed in the DBR layers Did result in increased ESP.
- (f) Added AlGaAsP spacer layer to the Phase I structure got high ESP and QE.

Summary

- Our initial efforts in Phase I established a robust baseline, achieving 85% ESP and a 4.5% QE. These results provided a strong foundation for further exploration and optimization.
- **→** Phase II Exploration: Pushing the Boundaries
- ➤ Building on the successes of Phase I, our objectives for Phase II focused on exploring the device growth and structure phase space to concurrently enhance both ESP and QE.
- > Superlattice Strain Experimentation
- During Phase II, we investigated the impact of increasing strain within the superlattice structure. This strategic adjustment yielded significant improvements in quantum efficiency, with **QE reaching as high as 13%**. While this demonstrated a promising avenue for QE enhancement, it unfortunately came at the cost of reduced ESP.
- ➤ While confined in design analysis we can also infer that minor composition changes and DBR thickness variations can greatly affect performance in the future production tool would benefit the works with greater in-situ feedback
- > Returning to the Phase I Structure: Optimizing for Balance
- ➤ Recognizing the need to maintain high ESP while improving QE, we decided to Phase I incorporation of an Phase II **AlGaAs spacer layer**. This decision proved beneficial, allowing us to successfully demonstrate **ESP** > 80% while simultaneously achieving a QE of ~ 5.5%. This represents a significant step forward, showcasing our ability to balance critical performance metrics.
- Last few tests are scheduled in the following months are a. Test remaining wafers & b. BNL will measure a sample in its gun in the accelerator facility.

Next steps...

- >Send samples to DOE labs for characterization of spin-polarized photocathodes.
- Test Photocathodes in actual accelerator gun at BNL (planned pending system availability) and other facilities.
- ➤ To significantly advance the performance of spin-polarized photocathodes, **Phase IIB** if possible, with funding from the DOE.
- ➤ To fully validate our findings and ensure the robustness of our structure Optimize uniformity and Set quality control for commercialization.
- This will represent a substantial step towards meeting the high-performance requirements for future spin-polarized electron sources in various DOE and other applications.

THANK YOU

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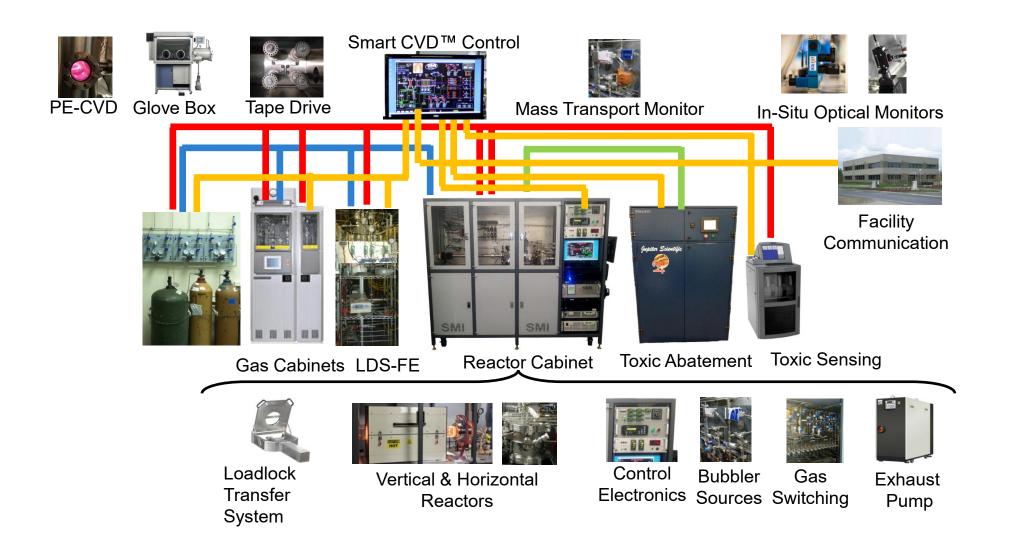
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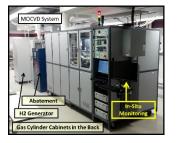
Anneal



VLSI



Horizontal 2D



III-V- II/VI



ALD



Cluster Tool



FB - CVD



HTS Tape



Nitrides / Carbides



Rebuilds & Conversions



ICP-CVD

Control Systems: Process Control Features Digital and Analog System

Well Controlled Process – Reproducible Product

Standard Features:

- Low Cost
- Based on commercial software products
- Graphical User Interface in Microsoft Windows environment
- Real time interactive mimic panels of the process system
- Spread sheet interface for process configuration
- Advanced alarm monitoring and management
- Password protection for operator interface

Optional Features

- Real time data logging and displaying
- Network support for distributed control system
- Automated process documentation generation
- Flexible hardware interface (PLCs, commercial instruments, etc...)
- In-Situ Process Monitoring and Interactive Control
- On-Line (Remote) operation, diagnostics, and upgrades
- Maintenance Procedures- Resource Consumption
- Sample/Wafer Tracking
- MECS/SECS Compatibility
- Remote access havend networking.

SMI Fabricated Devices & Structures



Tunable X-**Band Filter**



Battery made from Cathode Material

CBRAM GeS: Ag on



InN/Graphene **Gas Sensor**



Display **Electrodes**



SuperConductor Tapes



150mm PZT

Blue LED with



Graphene Sensor



Superior LED **Contacts**

Bulk Crystal

Fabrication



Missile **ARCs**



SRAMs and **FRAMs**

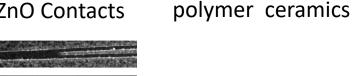
Si Photonics



Light Culminating Reflectors



ZnO Contacts



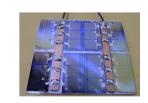
LiNbO3 Waveguide Modulator



CNT Structures SMI Logo in CNTs



Graphene Speaker



PhotoVoltaics & **ThermoPhotoVoltaics**



GE Dome Coating



FB-CVD coated with $Ti_{0.5}Si_{0.5}O_2$



SMI International Commitment to Customer































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systems

Materials



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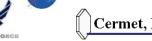
Components

Services













WRIGHT STATE





NST











FUJITSU











♦ spectalis





TriQuint (SEMICONDUCTOR





CORNING





Raytheon









Canadian Nuclear





TOLEDO



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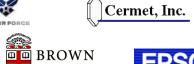
























SHARP.







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